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10665651

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THIN AND HEAT RADIANT SEMICONDUCTOR PACKAGE AND

METHOD FOR MANUFACTURING

First Named Inventor:

Jae Ku

Domestic/Foreign Application:

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Title of Invention

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10/665651

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Jae Hun Ku

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Submitted by:	Elec. Sign.	Sign. Capacity	
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney	

Documents being submitted

Files

us-ids

ids6-usidst.xml

us-ids.dtd

us-ids.xsl

Comments



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18 Stylesheet Version v18.0

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Art Unit:

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(6395578 or 6400004 or 6410979 or 6414385 or 6420779 or 6429508 or 6437429 or 6444499 or 6448633 or 6452279 or 6464121 or 6476469 or 6476474 or 6482680 or 6498099 or 6498392 or 6507096 or 6507120 or 6534849 or 6559525

or 6566168).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6395578	2002-05-28	SHIN ET AL.			
	2	6400004	2002-06-04	FAN ET AL.			
	3	6410979	2002-06-25	ABE			
	4	6414385	2002-07-02	HUANG ET AL.			
	5	6420779	2002-07-16	SHARMA ET AL.			
	6	6429508	2002-08-06	GANG			
	7	6437429	2002-08-20	SU ET AL.			
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	10	6452279	2002-09-17	SHIMODA			
	11	6464121	2002-10-15	REIJNDERS			·
	12	6476469	2002-11-05	HUNG ET AL.			
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	19	6534849	2003-03-18	GANG
	20	6559525	2003-05-06	HUANG
	21	6566168	2003-05-20	GANG

Signature

Examiner Name	Date

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